

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An optical module, comprising:
an optical subassembly including a semiconductor optical device;
a substrate securing the optical subassembly and mounting a circuit for driving the semiconductor optical device, the circuit generating heat;
a metal base enclosing the optical subassembly, the base providing an opening for exposing the circuit;
a metal cover ~~made of metal~~; and
a thermal block made of metal for dissipating the heat generated by the circuit, the thermal block arranged so as to ~~lie~~ cover the opening of the base and being thermally in contact with the circuit and the cover; and
a thermal sheet put between the thermal block and the circuit.
2. (Cancelled)
3. (Cancelled)
4. (Currently Amended) The optical module according to claim 3 ~~1~~, wherein the thermal sheet is made of ~~insulator~~ resin.
5. (Cancelled)
6. (Cancelled)

7. (New) The optical module according to claim 1,

wherein the opening has an inner surface sloped from the cover to the substrate.

8. (New) The optical module according to claim 7,

wherein the thermal block is secured by pressing an outer surface thereof to the inner surface of the opening.